

# XPS study of the thermal vapour sulfurization of tungsten thin films

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## ABSTRACT

Here we report the XPS spectra of thermally sulfurized tungsten thin films on SiO<sub>2</sub> at different temperatures. The sulfurization was performed in a chemical vapour deposition system at 400 °C, 500 °C, 550 °C, 600 °C and 750 °C. Below 500 °C XPS showed that the tungsten layer was oxidized (W<sup>6+</sup>) and only carbon-sulfur compounds were detected. On the other hand, from 600 °C the sulfurization process was complete by forming WS<sub>2</sub>, while at the intermediate temperature of 550 °C the films were partially oxidized and partially sulfurized.

## 1. INTRODUCTION

Transition metal dichalcogenides (TMDs) are quite promising 2D materials due to their amazing properties [1-4]. They follow the general form of MX<sub>2</sub> in which M and X are transition metal and chalcogen atoms, respectively. Among others transition metals, molybdenum and tungsten are the most used, producing MoS<sub>2</sub> and WS<sub>2</sub> when sulfurized, respectively. Nowadays, these materials are subject of intense research around the world due to the broad range of their possible applications [5]. Thus, several applications in fields such as nanoelectronics [1], optoelectronics [6], spintronics [6] and energy conversion [7,8], among others, have been proposed. Nevertheless, the development of low-cost techniques for synthesising thin films of TMDs for the above-mentioned applications remains an ongoing challenge.

The most used methods for the synthesis of TMDs are liquid exfoliation [9] and chemical vapour deposition (CVD) [9,10], which usually produce inhomogeneous samples. On the other hand, thermal vapour sulfurization (TVS) [11,12] seems to be better positioned for growing large-area high-quality TMDs. It consists in a two-step process in

which a transition metal is firstly deposited on a substrate and then sulfurized in a CVD system [11,13,14]. Nowadays, there is a huge research on both the method for pre-depositing the metal on a substrate as well as the conditions for its sulfurization [11]. In fact, metal deposition have been carried out by following different chemical and physical methods, such as drop coating, atomic layer deposition, sputtering, pulsed laser deposition and thermal evaporation [14].

In this work, we characterized by X-ray photoelectron spectroscopy (XPS) the TVS of tungsten layers at different temperatures to obtain WS<sub>2</sub>. Tungsten was deposited on SiO<sub>2</sub> by thermal evaporation from a filament under vacuum conditions. This report shows that W remains oxidized when the TVS is carried out at temperatures lower than 500 °C. On the other hand, for temperatures higher than 600 °C the TVS process is complete, forming WS<sub>2</sub> on SiO<sub>2</sub>.

## 2. METHODS

SiO<sub>2</sub> substrates were cleaned with acetone and ethanol in an ultra-sonic system.

A tungsten wire with a diameter of 0.25 mm was used for W thermal deposition on SiO<sub>2</sub> at an

electrical current of 10 A under a pressure of  $5 \times 10^{-3}$  mbar.

The sulfurization was carried out in a CVD system, where sulfur powder was heated at 170 °C while the sample temperature was ramped at 10 °C/min until reaching the target value. A combination of N<sub>2</sub> (4 l/h) and H<sub>2</sub> (1 l/h) was used during TVS at a pressure of 10 mbar.

XPS spectra were acquired in an Ultra High Vacuum (UHV) system with a base pressure of  $2 \times 10^{-10}$  mbar. The system is equipped with a hemispherical electron energy analyzer (SPECS Phoibos 150), a delay-line detector and a monochromatic AlK $\alpha$  (1486.74 eV) X-ray source. High-resolution spectra were recorded at normal emission take-off angle and with a pass-energy of 20 eV, which provides an overall instrumental peak broadening of 0.5 eV.

### 3. RESULTS

First, a desired quantity of tungsten was deposited on SiO<sub>2</sub> by thermal evaporation under vacuum conditions. This evaporation was performed by flowing an electric current through a tungsten filament. Then, the samples were introduced in a

CVD system for their sulfurization following an optimized procedure described in [11]. Roughly, the samples were introduced at the heating zone of a CVD system while an alumina boat containing S was located at the entrance of the quartz tube and independently heated.

Figure 1 shows a scheme of a tungsten thin film growth and its subsequent thermal vapour sulfurization.

The TVS of tungsten layers was followed by XPS. This technique allows to detect the elements at the sample and their chemical environment. Figure 2 shows the XPS results obtained after TVS at 400 °C, 500 °C, 550 °C, 600 °C and 750 °C. Figure 2a, 2b and 2c show the W 4f, S 2p and O 1s XPS regions, respectively. Moreover, W 5p<sub>3/2</sub> appears at higher binding energies (BE) of Figure 2a.

Two different regimes were identified by XPS, below 500 °C (black and red spectra in Fig. 2) and above 600 °C (blue and violet spectra in Fig. 2). Moreover, at an intermediate temperature of 550 °C (green spectra in Fig. 2) the shape of W 4f, S 2p and O 1s XPS spectra can be described as the convolution of the low and high temperature spectra (see below).

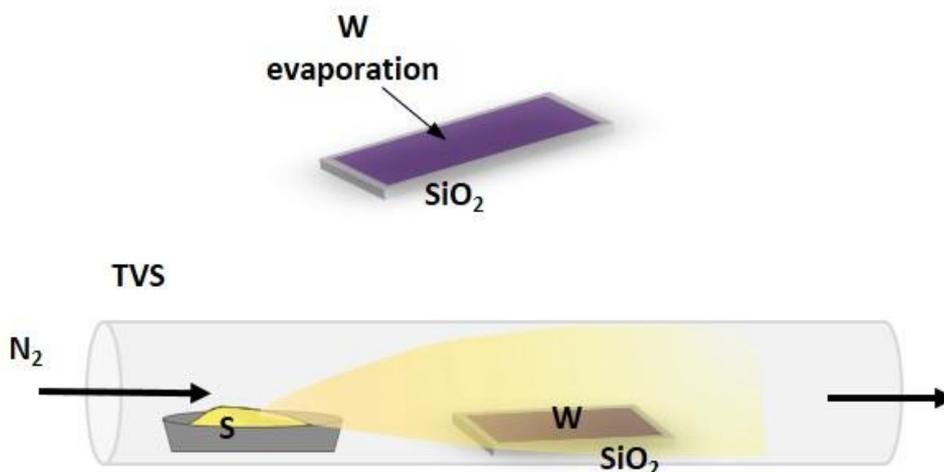


Figure 1. Scheme of the protocol used for growing WS<sub>2</sub> thin films. A pre-deposited W film on SiO<sub>2</sub> was thermally vapour sulfurized.

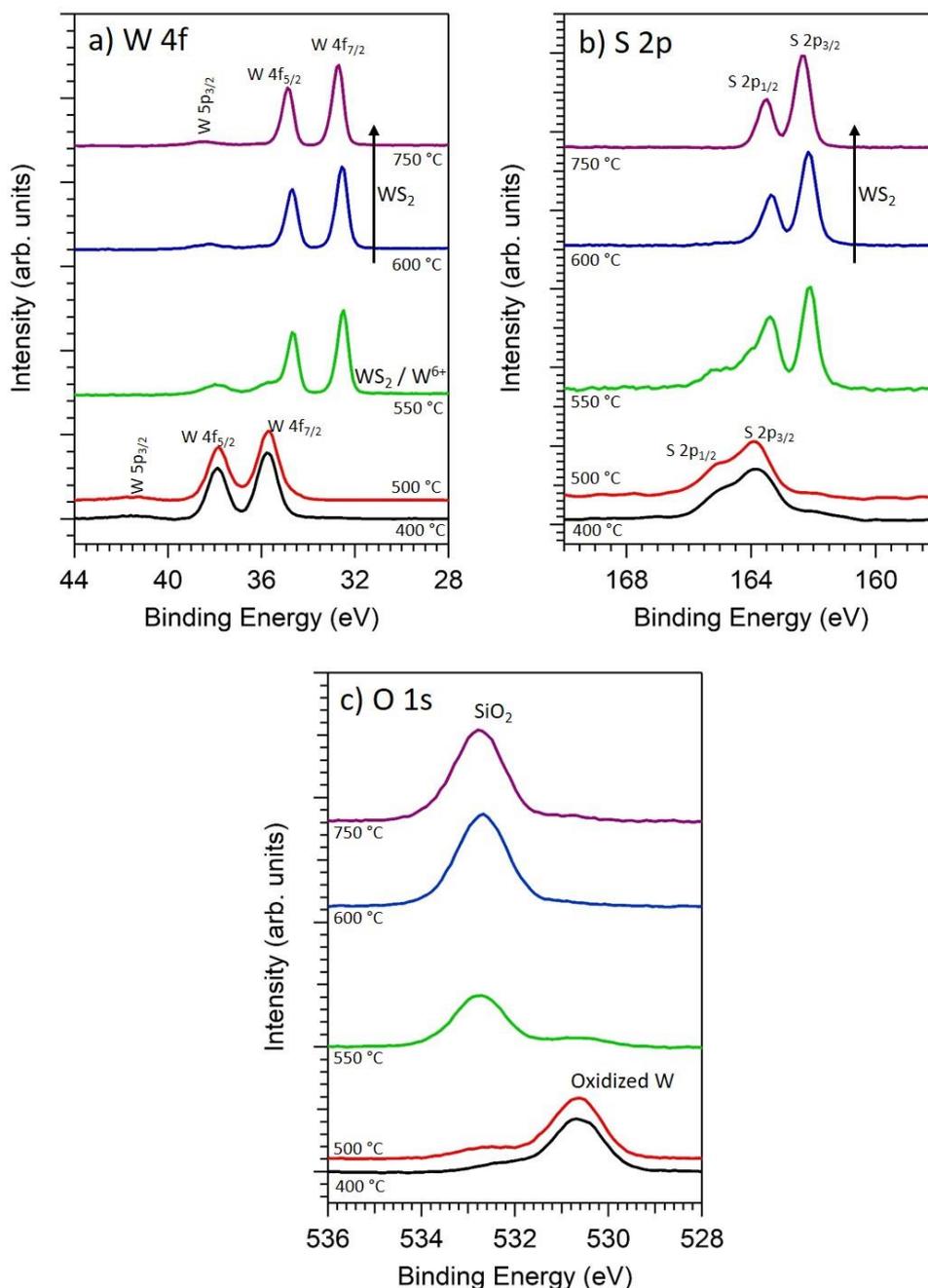


Figure 2. XPS normalized spectra of the tungsten thin film after thermal vapour sulfurization at 400 °C (black spectra), 500 °C (red), 550 °C (green) and 600 °C (blue) and 750 °C (violet). a) W 4f, b) S 2p and c) O 1s regions.

Below 500 °C, W 4f had two main XPS peaks centred at BEs of about 35.8 eV and 37.9 eV, ascribed to W 4f<sub>7/2</sub> and W 4f<sub>5/2</sub>, respectively. These BEs were in good agreement with previous reported values for oxidized tungsten *i.e.* W<sup>6+</sup> [15-18]. On the other hand, in the low temperature regime, S 2p showed two broad peaks centred at

BEs of about 163.9 eV and 165.1 eV corresponding with S 2p<sub>3/2</sub> and S 2p<sub>1/2</sub>, respectively. These BEs are higher than the expected values for S atoms in a WS<sub>2</sub> chemical environment (blue spectra of Fig. 2b). On the contrary, XPS indicated that at the low temperature regime, some sulphur atoms were deposited on oxidized tungsten film but not forming

WS<sub>2</sub>. In fact, these BE values are compatible with C-S species, suggesting the presence of some organo-sulfur compounds [19]. Importantly, the S/W ratio obtained by XPS at the low temperature regime was 0.58, significantly lower than that expected for WS<sub>2</sub>. Moreover, two peaks appeared in the O 1s region at BEs of about 532.8 eV and 530.7 eV. The peak at higher BE was ascribed to the oxygen atoms of the SiO<sub>2</sub> [20] substrate while the second peak corresponded with WO<sub>3</sub> [17,18].

A completely different scenario was obtained by XPS at temperatures higher than 600 °C in which both W 4f and S 2p strongly shifted to lower BEs. W 4f had two main peaks centred at BEs of about 32.6 eV (W 4f<sub>7/2</sub>) and 34.7 eV (W 4f<sub>5/2</sub>), values which were in good agreement with previous reported BEs for W atoms in a WS<sub>2</sub> chemical environment [15,16,21]. Moreover, the extra peak centred at a BE of 38.3 eV was ascribed to W 5p<sub>3/2</sub> from WS<sub>2</sub> samples [15,16,22]. Complementary, S 2p presented two sharp peaks at BEs of 162.2 eV (S 2p<sub>3/2</sub>) and 163.4 eV (S 2p<sub>1/2</sub>) as it was expected for sulfur atoms in WS<sub>2</sub> samples [15,16,21,22]. Thus, XPS indicated that WO<sub>3</sub> transformed into WS<sub>2</sub> after TVS at temperatures higher than 600 °C. Accordingly, the peak ascribed to WO<sub>3</sub> in the O 1s XPS region vanished in the high temperature regime (see Fig. 2c).

#### 4. CONCLUSIONS

XPS analysis of the thermal vapour sulfurization of oxidized tungsten thin films on SiO<sub>2</sub> showed that the reaction started at temperatures higher than 500 °C, although the complete transformation to WS<sub>2</sub> was obtained from 600 °C. Thus, at the intermediate temperature of 550 °C, the films were partially oxidized and partially sulfurized. In XPS spectra of WS<sub>2</sub> films obtained from 600 °C W 4f<sub>7/2</sub> was centred at a BE of around 32.6 eV while S 2p<sub>3/2</sub> appeared at 162.2 eV.

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